

Title (en)

Method of manufacturing tin plated strips or plates of copper or copper alloy

Title (de)

Verfahren zur Herstellung von verzinnnten Bändern oder Blechen aus Kupfer oder einer Kupferlegierung

Title (fr)

Procédé pour la fabrication de bandes ou de feuilles de cuivre ou à base d'un alliage de cuivre étamé

Publication

EP 0667403 B1 19970521 (DE)

Application

EP 95101331 A 19950201

Priority

DE 4404699 A 19940215

Abstract (en)

[origin: EP0667403A1] Prodn. of tinned copper (alloy) strip or sheet involves rolling the copper semi-finished strip product with a textured work roll to achieve an average roughness depth of 3-12 μm and continuously coating the strip with tin (alloy), such that the ratio of the average roughness depth to tin layer thickness is greater than 1.2, pref. greater than 2.

IPC 1-7

C25D 7/06; **C22F 1/08**; **C25D 5/34**; **C25D 3/30**; **C23C 2/08**; **C23C 2/40**

IPC 8 full level

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CPC (source: EP US)

B21B 1/227 (2013.01 - EP US); **C23C 2/08** (2013.01 - EP US); **C25D 5/34** (2013.01 - EP US); **B21B 2003/005** (2013.01 - EP US)

Cited by

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EP 0667403 A1 19950816; **EP 0667403 B1 19970521**; AT E153391 T1 19970615; AU 1226195 A 19950824; AU 687140 B2 19980219; CA 2141122 A1 19950816; CA 2141122 C 19981229; DE 4404699 A1 19950817; DE 59500243 D1 19970626; DK 0667403 T3 19971208; ES 2101589 T3 19970701; FI 111651 B 20030829; FI 950668 A0 19950215; FI 950668 A 19950816; GR 3023527 T3 19970829; JP 3365695 B2 20030114; JP H07331484 A 19951219; NO 309156 B1 20001218; NO 950552 D0 19950214; NO 950552 L 19950816; US 5580617 A 19961203

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